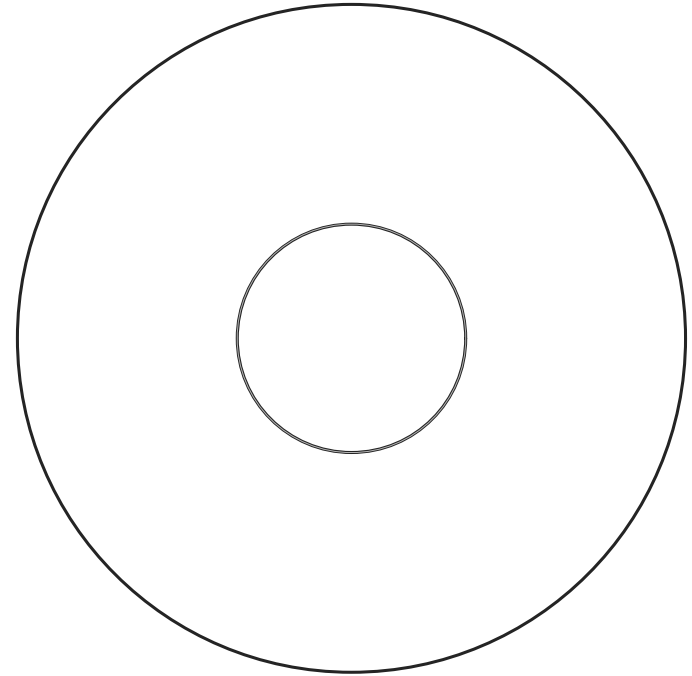


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01496	REV: E2	SUN REV: Not In VersionControl
	TID #: TIDA-01496		
PLOT NAME = Top Assembly Drawing	GENERATED : 4/17/2018	9:18:44 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01496	REV: E2	SUN REV: Not In VersionControl
	TID #: TIDA-01496		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/17/2018	9:18:45 PM	TEXAS INSTRUMENTS

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